
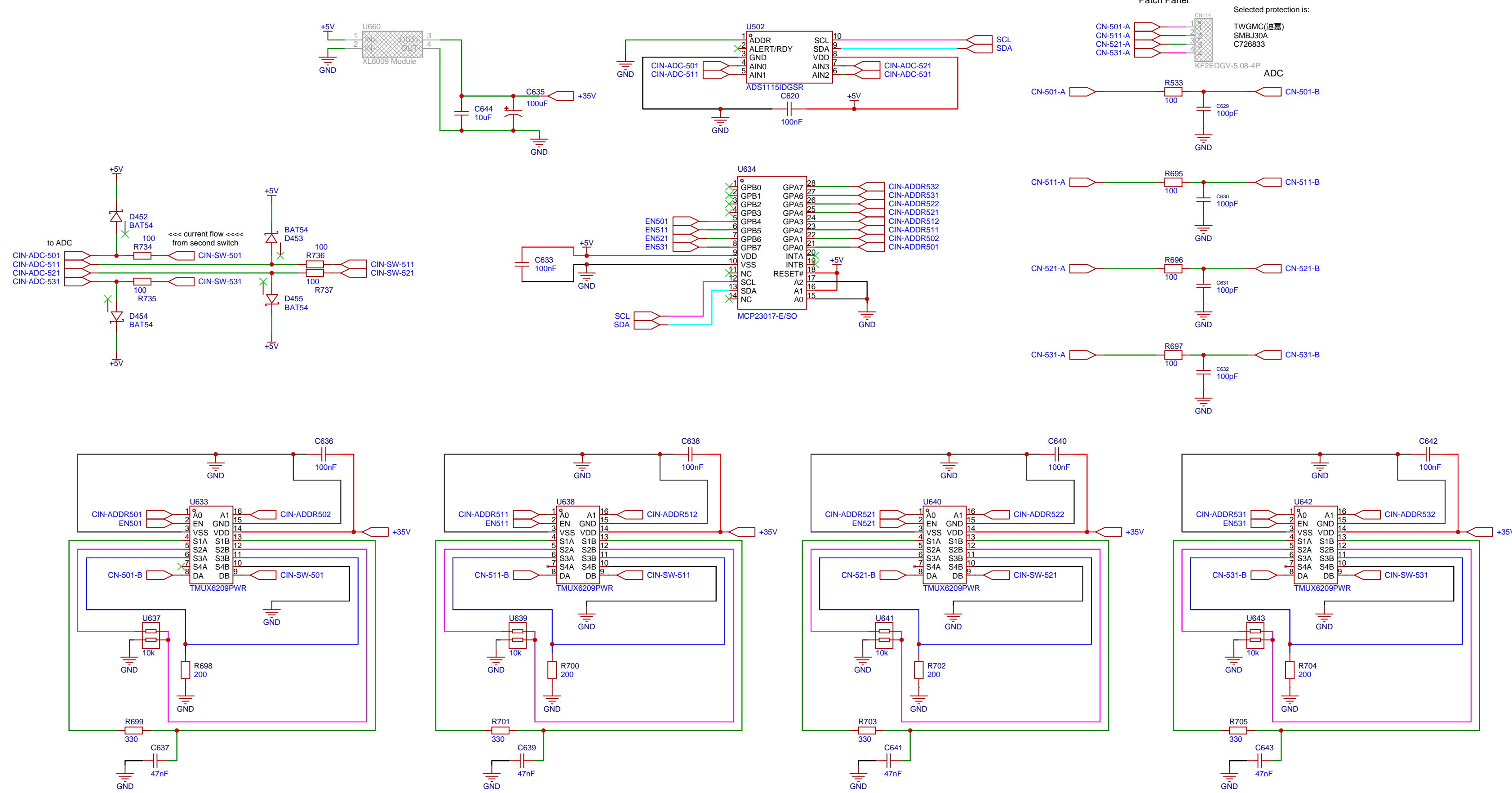


- This schematic defines four analog output channels with flexible signal selection, op-amp buffering, and ESD protection routed to a labeled patch panel.
- \* The MCP4728 DAC (U601) provides four independent analog voltage outputs (CH1 – CH4).
    - I2C-controlled; fixed address default is 0x60 (EEPROM can be used to reassign).
    - Output range: 0 to 5V referenced to GND.
    - Local bypass capacitor (C601 = 100nF) stabilizes the supply.
  - \* The PCA9685 PWM controller (U603) supplies four PWM outputs and four select lines.
    - I2C address set to 0x40.
    - Channels LED0,2,4,6 provide PWM signals (CHx-DOUT-PWM).
    - Channels LED1,3,5,7 control signal selection (CHx-DOUT-SEL).
    - Duty cycles can be set to 0% or 100% for use as digital outputs.
    - Decoupling capacitor (C603 = 100nF) placed at VDD.
  - \* Each channel includes an SPDT analog switch (U646 – U649, SN74LVC1G3157DCKR).
    - B1 input receives CHx-DAC-OUT.
    - B2 input receives CHx-DOUT-PWM.
    - S input is driven by CHx-DOUT-SEL (from PCA9685).
    - S = 0 selects DAC (analog), S = 1 selects PWM (digital).
    - Local decoupling capacitors (C610 – C613, 100nF) stabilize each switch.
  - \* The selected signal is buffered by a precision op-amp (U645 – U648, OPA333) configured for unity gain.
    - Provides low-impedance drive suitable for analog or digital outputs.
    - Series resistor (49.9  $\Omega$ ) on each output adds protection and improves signal integrity.
    - H2 - H5 Provide an option to include the op amp or bypass it.
      - Jumping 1-2 & 3-4 will include the op amp in the output circuit
      - Jumping 1-3 will bypass the op amp entirely
  - \* Outputs are routed to a 4-pin patch panel connector (CN111).
    - Each channel output is labeled CHx-PATCH-PANEL-OUT.
    - Connector part: KF2EDGV-5.08-6P, labeled " Analog Out Patch Panel " .
  - \* ESD protection is provided on each output using unidirectional TVS diodes (D441 – D444, PESD5V0S1UL).
    - Designed for ESD transient suppression to IEC 61000-4-2.
    - Clamping behavior protects against brief high-voltage events.
    - Diodes are placed near the connector to suppress external transients.
  - \* Ground is shared across DAC, PWM, switching, and analog output stages.  
Proper layout isolation is recommended to minimize cross-domain noise coupling.
  - \* This design enables software-defined analog output routing:
    - Use DAC for stable analog voltage output.
    - Use PWM or static logic for digital control signals.
    - Outputs are selectable per channel, with seamless runtime switching.

|  |            |      |                  |             |
|--|------------|------|------------------|-------------|
| Schematic  | Schematic1 |      | Create at        | 2025-08-27  |
| Board  | Main       |      | Update at        | 2025-09-07  |
| Drawn  |            |      | Page             | Analog Out  |
| Reviewed   |            |      | Practice 4 layer |             |
|  |            |      |                  |             |
|  | Version    | Size | Page 2 Total 5   |             |
|  <b>EasyEDA</b> |            | V1.0 | A4               | EasyEDA.com |





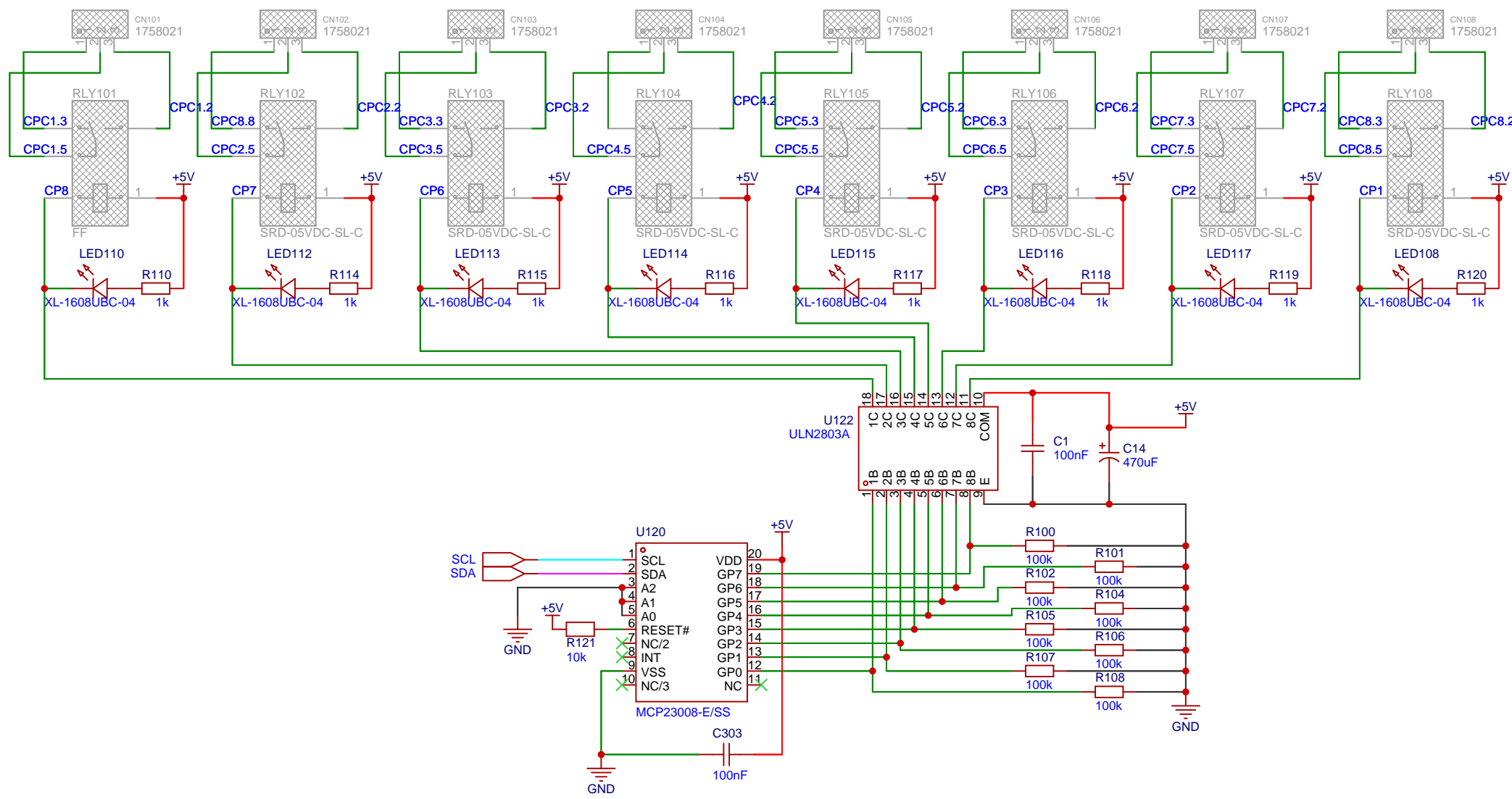
DRAWING NOTES – SHEET 500 (INPUT PROTECTION AND SWITCH ROUTING)

- \* This circuit protects and routes 4 analog input channels from a patch panel through a selectable analog conditioning path and into a shared ADC.
- \* Signals enter from the patch panel at headers CN-501, -511, -521, and -531.
- \* Each signal passes through a 100 series resistor to limit inrush and fault current.
- \* Schottky diodes (D452 – D455, BAT54) clamp each signal to the +5 V rail:
  - Diodes are placed after the 100 resistor to safely shunt overvoltage events.
  - Forward voltage is ~0.3 V, providing early clamping around 5.3 V max.
- \* Clamped signals continue through labeled nets CIN-SW-501 through CIN-SW-531 to analog switches (TMUX6209).
- \* Signals are routed via the selected switch to a signal conditioning circuit:
  - Options include direct voltage, 2:1 divider, 4 – 20 mA loop, or ground sense.
  - Only one path is active per input channel at a time.
- \* After conditioning, signals are routed through a second switch stage and finally into the ADC (ADS1115) for digitization.
- \* The 100 series resistors:
  - Limit current into the BAT54 clamp during faults.
  - Provide high-frequency damping.
  - Have negligible effect on signal quality at ADC sampling rates.
- \* This configuration protects the ADC and muxes from accidental overvoltage, miswiring, or unexpected signal conditions.
- \* Clamp strategy assumes inputs remain above GND; reverse protection is not implemented.

PROGRAMMER NOTES – SHEET 500: ANALOG INPUT SYSTEM

- \* The TMUX6209 (U633) is controlled via 3 digital signals: A0, A1, and EN.
  - These are driven by GPIO pins from the I<sup>2</sup>C GPIO expander \(\MCP23017, U634\).
  - The EN signal should be deasserted (LOW) before changing A0/A1 to avoid glitches or mid-switch artifacts.
  - Wait at least 10 μs after switching before sampling to allow analog settling.
- \* Only one signal conditioning path should be active at a time per channel.
  - Valid selections: 00, 01, 10, or 11 (see conditioner map in software).
  - EN must be HIGH to activate the selected signal path.
- \* The ADS1115 \(\U502\) is configured over I<sup>2</sup>C and supports 4 single-ended inputs \(\AIN0 – AIN3\).
  - Address is fixed at 0x48.
  - Use single-shot mode unless fast continuous conversion is required.
  - Default full-scale range is ±6.144 V; set to ±4.096 V or lower for best resolution with 0 – 5 V inputs.
  - Configure MUX bits to select the correct AINx channel.
  - Use 860 SPS for quick response or 128 SPS for higher noise immunity.
- \* Current loop inputs (4 – 20 mA path):
  - Use software scaling: 4 mA = 0 V; 20 mA = V<sub>burden</sub> (typically 2 V).
  - Apply calibration factors in firmware to correct for resistor tolerances.
- \* Calibration and Filtering:
  - Optional RC filters (~10 kHz cutoff) are present at analog outputs of conditioner paths.
  - Additional digital filtering (e.g. IIR or EMA) is recommended in firmware to reject noise or jitter.
- \* Power-On State:
  - Ensure all EN signals are LOW at power-on.
  - Do not leave multiple conditioning paths active simultaneously — this may cause signal contention or distortion.





Drawing Notes — Relay Driver Circuit

\* This sheet defines the relay driver circuit, including relay control, flyback protection, indicator LEDs, and I²C interface to the MCP23008 GPIO expander.

MCP23008 GPIO Expander (U120)

- \* The MCP23008 provides 8 GPIO lines via the I²C interface.
- \* I²C address is set to 0x20 via address pins A2, A1, A0 \ (all tied LOW).
- \* External 10k pull-ups on SDA and SCL are required if not already provided elsewhere on the bus.
- \* A 100nF decoupling capacitor (C303) is placed near VDD.
- \* GPIOs default to Hi-Z input mode at power-up. Until firmware configures the pins as outputs, they are not actively driven.

Relay Driver and Inversion Behavior

- \* GPIO outputs from the MCP23008 are connected to the ULN2803A Darlington array (U122), which drives eight 5V relay coils.
- \* The ULN2803A is electrically inverting:
  - Input HIGH Output LOW (GND)
  - Input LOW Output floating (open)
- \* In this configuration, the relay coils are connected between +5V and ULN outputs, so the circuit behaves logically non-inverting:
  - MCP output HIGH Relay ON
  - MCP output LOW Relay OFF

Startup Behavior and Pull-Down Resistors

- \* At startup, the MCP23008 GPIOs are not yet configured, and remain in Hi-Z state.
- \* 100k pull-down resistors (R100 – R108) are placed on the inputs of the ULN2803A, ensuring that the ULN inputs are held LOW during this time.
- \* This prevents unintended relay activation before firmware takes control and ensures relays are OFF at boot.

Firmware Programming Requirements

- \* Firmware must:
  1. Configure MCP23008 GPIOs as outputs: IODIR = 0x00
  2. Optionally initialize output latch register: OLAT = 0x00 to start with all relays OFF
  3. Use GPIO writes to control relays:
    - Write 1 (HIGH) Relay ON
    - Write 0 (LOW) Relay OFF

Relay and LED Circuitry

- \* Relay Type: SRD-05VDC-SL-C
  - 5V coil
  - SPDT contacts
  - Coil resistance: ~70
- \* Each relay drives an indicator LED (LED110 – LED117) in parallel with the coil, via a 1k series resistor (R110 – R117), illuminating when the relay is ON.
- \* The ULN2803A includes internal flyback diodes, protecting against inductive spikes from the relay coils.

Terminal Blocks and Contact Isolation

- \* Each relay 's output is routed to a 3-pin terminal block (CN101 – CN108).
- \* Relay contacts are electrically isolated from control and logic sections.
- \* Contact naming follows the CPCx.y convention:
  - Example: CPC1.3 = Relay 1 NC contact

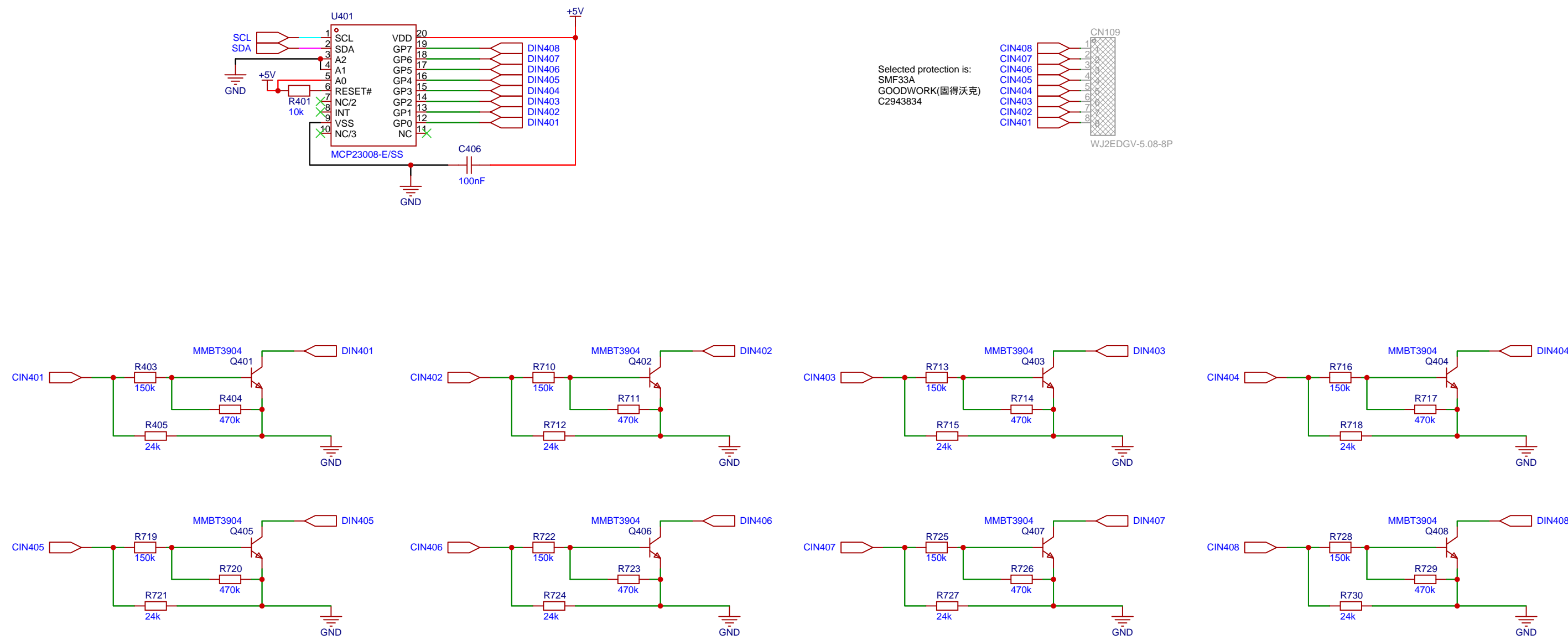
Power and Decoupling

- \* Relay coils are powered from +5V via ULN2803A.
- \* Local decoupling:
  - C1 = 100nF ceramic
  - C14 = 470µF electrolytic
  - Both placed near U122 to ensure supply stability during relay switching

Grounding and Power Plane Notes

- \* Logic, relay drivers, and relay coils share a common GND.
- \* PCB layout should isolate high current relay paths from noise-sensitive logic and I²C traces.
- \* If needed, use local copper fills or stitching vias to create a return path with low inductance near the ULN outputs.





\* This sheet defines 8 isolated digital input channels, protected and level-shifted for monitoring via I2C.

- \* Input connector CN109 receives 8 external digital signals (CIN401 – CIN408).
- Each input line is protected with a SMF33A TVS diode to ground.
- TVS clamps only above ~36V, suitable for 24V or higher industrial systems.
- Inputs are filtered and routed through individual level-shift circuits.

- \* Each input line (CIN401 – CIN408) is processed by a discrete NPN transistor stage (Q401 – Q408).
- Transistor type: MMBT3904
- Input resistor: 150k (limits input current)
- Base divider: 150k / 24k to set logic threshold near 5V
- Pull-down resistor: 470k ensures input goes low when unconnected
- Outputs (DIN401 – DIN408) are open-collector logic-level signals

- \* Processed outputs (DIN401 – DIN408) feed into the MCP23008 GPIO expander (U401).
- MCP23008 address pins (A0, A1, A2) are configured via hard-wired levels to address 0x21
- I2C interface connects to SDA/SCL and is pulled up externally
- Decoupling capacitor (C406 = 100nF) is placed near VDD
- Internal RESET is pulled up via 10k resistor (R401)

- \* The MCP23008 digitizes the input states for I2C monitoring.
- Outputs are active-low, reflecting the collector state of each NPN stage
- 5V logic compatible, shared with host I2C bus

\* GND is the reference for all comparator stages and is assumed shared with the incoming signal ground.

\* This circuit provides robust overvoltage protection, signal conditioning, and digital isolation for interfacing field-level signals with a microcontroller or embedded system via I2C.

- \* Programming Notes:
- Each input pin (DIN401 – DIN408 GP0 – GP7) should be configured as an **\*\*input\*\***:
- ``IODIR = 0xFF``
- Enable **\*\*internal weak pull-ups\*\*** (typical 100k , ~25 μs rise time with 50pF):
- ``GPPU = 0xFF``
- Input logic is **\*\*active-low\*\***:
- ``0 = active/high input``, ``1 = inactive/low input``
- Software should **\*\*invert logic\*\*** when interpreting input state